



PATENT
Attorney Docket No. 401346/FUKAMI

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

HIDEYUKI ARAKAWA

Application No. 09/934,643

Art Unit: 2823

Filed: August 23, 2001

Examiner: H. Lee

For: SEMICONDUCTOR DEVICE AND
MANUFACTURING METHOD
THEREOF

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12/21/02
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TECHNICAL STAFF

RESPONSE TO OFFICE ACTION

Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

In response to the Office Action dated September 4, 2002, please enter the following amendments and consider the following remarks.

AMENDMENTS

IN THE CLAIMS:

Cancel claims 2, 3, 8, and 8 and replace the indicated claims with:

- BI
Pub
C'1
1. (Twice Amended) A semiconductor device, comprising:
a first conductive layer;
a first contact comprising a ball on said first conductive layer;
a second conductive layer spaced apart from said first conductive layer;
a second contact on said second conductive layer; and
a bonding wire connecting said first contact and said second contact, wherein said second contact includes at least two layers of said bonding wire, lying directly on each other, said bonding wire including at least one reverse bend.